IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant(s): HAMASAKI Atty. Dkt.: 01-615

Serial No.: Unknown Group Art Unit:

Filed: Concurrently herewith Examiner:

Title: METHOD OF RESIN-SEALING A

SEMICONDUCTOR DEVICE.

RESIN-SEALED

SEMICONDUCTOR DEVICE, AND

FORMING DIE FOR RESIN-

SEALING THE SEMICONDUCTOR

DEVICE

Date: April 1, 2004

Commissioner for Patents Arlington, VA 22202

INFORMATION DISCLOSURE STATEMENT

Sir:

Pursuant to 37 C.F.R. §1.56, the reference(s) listed on the attached Form PTO-1449 is/are submitted for consideration by the Examiner without any admission that it/they constitute(s) statutory prior art, or without any admission that it/they contain(s) subject matter that anticipates the invention or renders the invention obvious to a person of ordinary skill in the art.

The Examiner is requested to initial the attached PTO Form-1449 and to return a copy of same to the undersigned attorney as proof that the listed reference(s) has/have been considered and made of record.

Respectfully submitted,

David G. Posz Reg. No. 37,701

Posz & Bethards, PLC 11250 Roger Bacon Drive, Suite 10 Reston, VA 20190 (703)707-9110 (phone) Customer No. 23400

* PATENT APPLICATION

Page 1 of

				1 age 1 Of 1
FORM PTO-1449	ATTY. DKT NO.	01-615	SER. NO.	
	APPLICANT	HAMASAKI		
	FILING DATE	April 1, 2004	GROUP	

REFERENCE DESIGNATION

U.S. PATENT DOCUMENTS

EXAMINER INITIAL	DOCUMENT NUMBER	DATE	NAME	CLASS	SUB CLASS
	5,077,237	July 8, 1997	Hara		

FOREIGN PATENT DOCUMENTS

TRANSLATION

	TIGHTOEATION							
DOCUMENT NUMBER	DATE	COUNTRY	NAME	CLASS	SUB CLASS	YES	NO Eng.	
JP-A-2-297946	12/10/90	JAPAN					Abstract	
JP-A-2000-58573	2/25/00	JAPAN	,				Х	
JP-A-7-130782	5/19/95	JAPAN					X	
				:				

^{*} Full English text is available in machine-translated form in JPO (Japanese Patent Office) English language web site at http://www1.ipdl.jpo.go.jp/PA1/cgi-bin/PA1INDEX.

OTHER REFERENCES (including Author, Title, Date, Pertinent Pages, etc.)

EXAMINER	 	DATE CONSIDERED)	<u>.</u>	

Rev. 10/94 (Form 3.05)